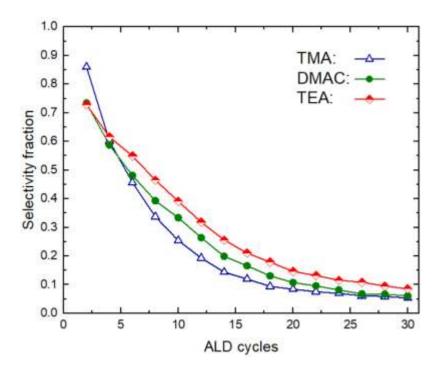


**Figure 1.** The thickness of  $Al_2O_3$  thin films on Si-H and Si-OH substrates at 200 °C deposited using trimethylaluminum (TMA), dimethylaluminum chloride (DMAC), or triethylaluminum (TEA) as a precursor and  $H_2O$  as a co-reactant. The thickness is measured using *in-situ* spectroscopic ellipsometry (SE).



**Figure 2.** Calculated selectivity fraction values between  $Al_2O_3$  films grown on Si-OH and Si-H starting surfaces using different Al precursor at 200 °C. The selectivity fraction is calculated as  $(t_1-t_2)/(t_1+t_2)$ , where  $t_1$  is the film thickness on the Si-OH and  $t_2$  the film thickness on the Si-H surface.